

Japan TC Chapter of Information & Control Global Technical Committee Liaison Report

As of January 24, 2018

Ver.1.0

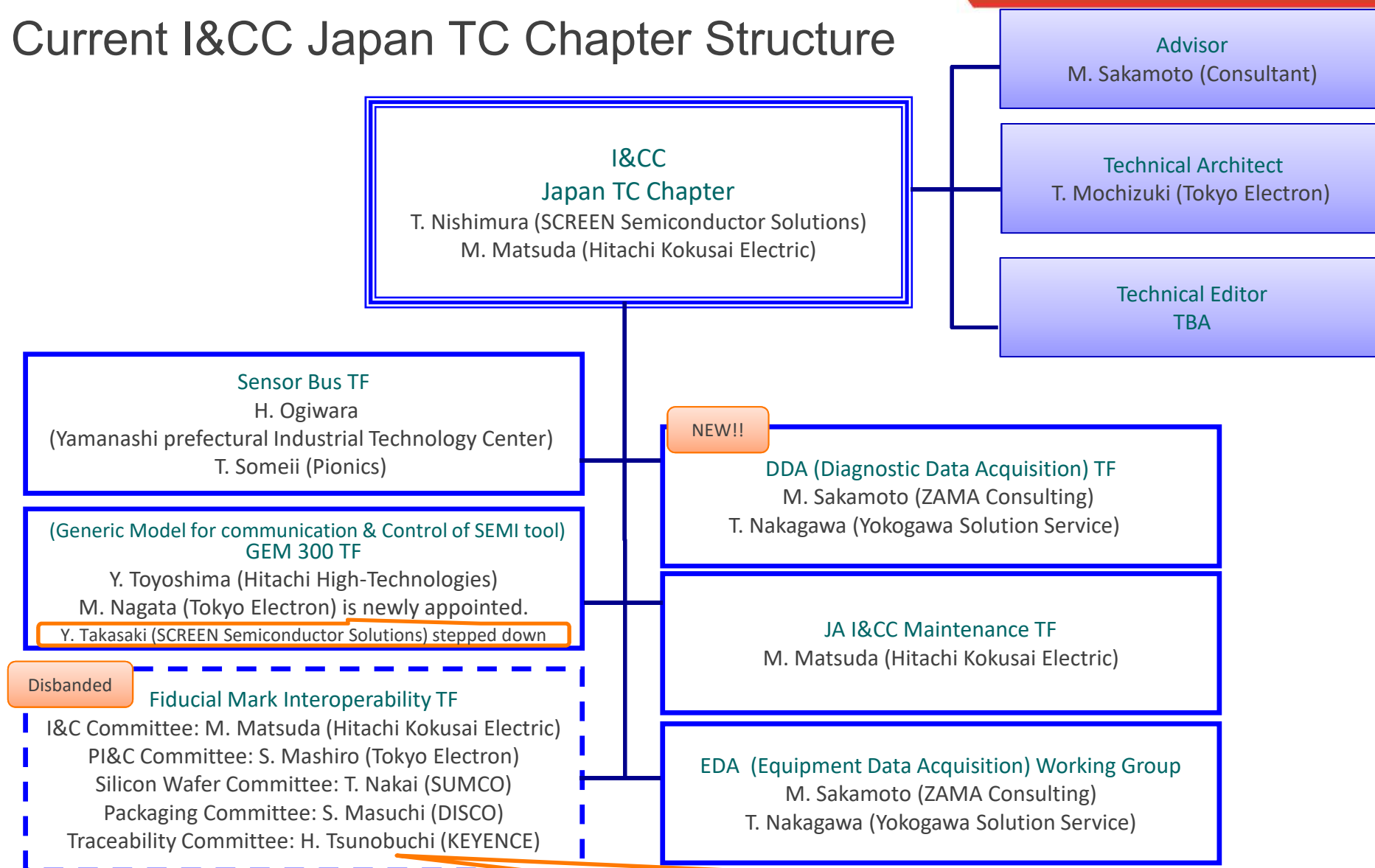
Outline

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I&CC Japan TC Chapter Leadership

- Co-chairs
 - Takayuki Nishimura / SCREEN Semiconductor Solutions
 - Mitsuhiro Matsuda / Hitachi Kokusai Electric
- Advisor
 - Mitch Sakamoto / Consultant
- Technical Architect
 - Tadashi Mochizuki / Tokyo Electron
- Technical Editor
 - TBA

Current I&CC Japan TC Chapter Structure



The TF is under the Japan TC Chapters of Silicon Wafers, PI&C, I&C, Traceability and Assembly & Packaging. The TF's discharge will be completed when agreed by all those TC Chapters. The Silicon Wafers agreed on March 9, Assembly & Packaging agreed on March 13 and PI&C agreed on April 19. The I&C agreed on April 21. The Traceability agreed on Dec 25. All of the TC Chapters agreed with the discharge of this task force.

Document Review Summary at SEMICON Japan 2017 Meetings

Doc #	Description	Committee Action
6202	Revision to SEMI E174-0817: Specification for Wafer Job Management (WJM)	Passed, as balloted
6287	Line Item Revision to E87-0312: Specification for Carrier Management (CMS)	
Line Item 1	Add reference/introduction/explanation statements of SEMI E171 Predictive Carrier Logistics (PCL)	Failed
Line Item 2	Add RELATED INFORMATION about SEMI E171 Predictive Carrier Logistics (PCL)	Passed, as balloted

SNARFs Approved at SEMICON Japan 2017 Meetings

Doc #	Description	TF
6319	Line Item Revision to E87-1017: Specification for Carrier Management (CMS)	GEM 300 TF
6324	Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS) TO CHAMGE THE MODEL DESIGN	GEM 300 TF
6325	Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS) TO DESCRIBE THE RELATION OF STRUCTURE OF MULTIPLE RECIPES	GEM 300 TF
6326	Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS), SEMI E170.1-mmyy: SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM and SEMI E5-mmyy: SEMI EQUIPMENT COMMUNICATIONS STANDARD 2 MESSAGE CONTENT (SECS-II)	GEM 300 TF

SNARFs Approved at GCS between SEMICON Japan 2017 Meetings and Japan Spring 2018 Meetings

Doc #	Description	TF
6330	Line Item Revisions to E54.17 Specification of Sensor Actuator Network for A-Link	Sensor Bus TF
6331	Line Item Revisions to E54.19 Specification of Sensor Actuator Network for MECHATROLINK	Sensor Bus TF

Ballots to be reviewed at Japan Spring 2018 Meetings

Cycle 2 – 2018		
Doc #	Description	TF
6319	Line Item Revision to E87-1017: Specification for Carrier Management (CMS)	GEM300 TF
6300	New Standard: Guide for EDA Freeze Version	DDA TF
6330	Line Item Revisions to E54.17 Specification of Sensor Actuator Network for A-Link	Sensor Bus TF
6331	Line Item Revisions to E54.19 Specification of Sensor Actuator Network for MECHATROLINK	Sensor Bus TF

Doc. #6324, Doc. #6325 and Doc. #6326 are postponed ballot submission.

Task Force Updates [1/7]

- Fiducial Mark Interoperability TF
 - Last TF meeting was held on November 18, 2015
 - Disbandment of this TF
 - TF leaders decided to propose disbanding this TF to each technical committee
 - If this proposal is agreed by all Japan TC Chapters of Assembly & Packaging, I&C, PIC, Silicon Wafers and Traceability, then the TF will be discharged.
 - The Silicon Wafers agreed on March 9, Assembly & Packaging agreed on March 13 and PI&C agreed on April 19. The I&C agreed on April 21. The Traceability agreed on Dec 25, 2017.
 - All of the TC Chapters agreed with the discharge of this task force.
 - Backend alignment issues with introducing fiducial mark wafer is left.
 - Would be discussed in Assembly & Packaging Japan TC Chapter after its disbandment.

Task Force Updates [2/7]

- GEM 300 TF
 - Last TF meeting was held on January 23, 2018.
 - #5973: Line Item Revision to SEMI E170 & SEMI E170.1
 - Ballot was reviewed at I&C Japan TC Chapter meeting on December 16, 2016.
 - LI 1 & LI 2 passed as balloted and passed A&R in January 2017.
 - LI 3 failed and work will be discontinued.
 - Published as E170-0517.
 - #6089: Line Item Revision to E170, E170.1 and E5
 - According to comment from potential Standards users at GEM300A STEP, TF consider to simplify E170 subordinate standard by using dedicated SECS II message, instead of OSS generic service.
 - Assumed stream number for E170.1 is S20.
 - SNARF was approved at I&C Japan TC Chapter meeting on October 21, 2016.
 - SNARF Revision was approved at I&C Japan TC Chapter meeting on December 16, 2016.
 - Ballot submitted for Cycle 2-2017 and passed at I&C Japan TC Chapter meeting on April 21, 2017.
 - Passed A&R in May, 2017.
 - Published as E5-1217, E170-1217 and E170.1-1217.
 - #6189: Line Item Revision to SEMI E170, E170.1 and E5
 - SNARF was approved at I&C Japan TC Chapter meeting on Apr 21, 2017.
 - E170 application Study Working Group was formed as a subgroup under GEM 300TF with leadership of Koji Kitajima (Toshiba Memory) and Masahide Hirouchi (IBM Japan).
 - Masahide Hirouchi (IBM Japan) was stepped down and Osamu Oishi (IBM Japan) is assigned as a CoLeader.

Task Force Updates [3/7]

- GEM300 TF (cont'd)
 - #6091: Line Item Revision to SEMI E174-1116
 - SNARF was approved at I&C Japan TC Chapter meeting on October 21, 2016
 - SNARF Revision was approved at I&C Japan TC Chapter meeting on December 16, 2016
 - Ballot submitted for Cycle 2-2017 and passed at I&C Japan TC Chapter meeting on April 21, 2017
 - Passed A&R in May, 2017
 - Published as E174-0817
 - #6202: Revision to SEMI E174-0817: Specification for Wafer Job Management (WJM)
 - SNARF was approved at I&C Japan TC Chapter meeting on Sep 21, 2017.
 - Ballot submitted for Cycle 8-2017 and passed at I&C Japan TC Chapter meeting on Dec 15, 2017

Task Force Updates [4/7]



6092_CUARAM

- GEM300 TF (cont'd)
 - #6092: New standard “CUARAM: Centralized User Authentication & Role Authorization Management”
 - Scope was discussed with EISS TF
 - SNARF was approved at I&C Japan TC Chapter meeting on October 21, 2016
 - Material of explanation for concept of CUARAM is distributed to global I&C TC Members in order to receive response from them.
 - #6287: SNARF for Line Item Revision to E87-0312: Specification for Carrier Management (CMS)
 - SNARF was approved at I&C Japan TC Chapter meeting on Sep 21, 2017.
 - Ballot submitted for Cycle 8-2017, and Line Item 2 passed at I&C Japan TC Chapter meeting on December 15, 2017. Line Item 2 failed.

Task Force Updates [5/7]

- GEM300 TF (cont'd)
 - #6319: Line Item Revision to E87-1017: Specification for Carrier Management (CMS)
 - SNARF was approved at I&C Japan TC Chapter meeting on December 15, 2017
 - #6324: Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS) TO CHANGE THE MODEL DESIGN
 - SNARF was approved at I&C Japan TC Chapter meeting on December 15, 2017
 - #6325: Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS) TO DESCRIBE THE RELATION OF STRUCTURE OF MULTIPLE RECIPES
 - SNARF was approved at I&C Japan TC Chapter meeting on December 15, 2017
 - #6326: Line Item Revision to SEMI E170-mmyy: SPECIFICATION FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM (SFORMS), SEMI E170.1-mmyy: SPECIFICATION FOR SECS-II PROTOCOL FOR SECURED FOUNDATION OF RECIPE MANAGEMENT SYSTEM and SEMI E5-mmyy: SEMI EQUIPMENT COMMUNICATIONS STANDARD 2 MESSAGE CONTENT (SECS-II)
 - SNARF was approved at I&C Japan TC Chapter meeting on December 15, 2017

Task Force Updates [6/7]

- JA I&CC Maintenance TF
 - Last TF meeting was held on October 21, 2016.
 - #6090: Line Item Revision to SEMI E91 (PSEM)
 - SNARF was approved at I&C Japan TC Chapter meeting on October 21, 2016.
 - Ballot submitted for Cycle 2-2017 and to be reviewed at I&C Japan TC Chapter on April 21, 2017
 - Passed A&R in May, 2017
 - Published as E91-1217
 - The activity of SEMI E107 “Specification of Electric Failure Link Data Format for Yield Management System”
 - No action to be made.

Task Force Updates [7/7]

- Sensor Bus TF
 - TFOF for Sensor Bus Task Force was approved at I&C Japan TC Chapter meeting on June 8, 2017
 - Last TF meeting was held on January 18, 2018.
 - #6330: SNARF for Line Item Revisions to E54.17 Specification of Sensor Actuator Network for A-Link
 - SNARF was approved at GCS on January 10, 2018.
 - Ballot to be submitted to Cycle 2, 2018.
 - #6331: SNARF for Line Item Revisions to E54.19 Specification of Sensor Actuator Network for MECHATROLINK
 - SNARF was approved at GCS on January 10, 2018.
 - Ballot to be submitted to Cycle 2, 2018.
- DDA (Diagnostic Data Acquisition) Task Force
 - TFOF for DDA TF was approved at I&C Japan Chapter TC chapter meeting on Sep 21, 2017.
 - Last TF meeting was held on December 15, 2017.
 - #6300: SNARF for New Standard: Guide for EDA Freeze Version
 - SNARF was approved at GCS on October 24, 2018.
 - Ballot to be submitted to Cycle 2, 2018.

Meeting Information - Japan TC

- Last Meeting – SEMICON Japan 2017 Meetings:
 - Friday, December 15, 2017 1:00PM-5:00PM
 - @ Tokyo Big Sight, Tokyo, Japan
- Next Meeting –Japan Spring 2018 Meetings:
 - Thursday, April 26, 2018 1:30PM-5:00PM
 - @ SEMI Japan Office, Tokyo, Japan

Schedule for I&CC Japan TC Chapter Meetings

- Spring on April 26th, 2018
- Summer on June 2018
- Fall on September 2018
- Winter on December 14th, 2018 (tentative)
 - in conjunction with SEMICON Japan 2018

*End of
I&CC Japan TC Chapter
Liaison Report
Thank You!*

*For more information, please contact
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(miwamura@semi.org)*

Back Up

Announcement

- GEM300A
 - SEMI E170 SFORM, SEMI E171 PCL and SEMI E174 WJM document group was named “GEM300A”.
- EDA(Equipment Data Acquisition) Working Group
 - To form EDA WG was approved at I&C Japan Chapter TC chapter meeting on Apr 21, 2017.
 - Kick-off meeting was held on June 8, 2017.